ABSOLUTE MAXIMUM RATINGS

IN, SHDN, RESET to GND	0.3V to +4.0V
OUT to GND	
Output Short-Circuit Duration	Continuous
Continuous Power Dissipation (multilaye	er board, TA = +70°C)
6-Pin SOT23 (derate 9.1mW/°C above	e +70°C)727mW
6-Pin TDFN (derate 23.8mW/°C above	
8-Pin TDFN (derate 11.9mW/°C above	e +70°C)953.5mW

Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Soldering Temperature (reflow)	+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{IN} = (V_{OUT} + 0.5V) \text{ or } 1.8V, \text{ whichever is greater}; \overline{SHDN} = IN, C_{IN} = 1\mu\text{F}, C_{OUT} = 4.7\mu\text{F}, T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at $T_A = +25^{\circ}\text{C}$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS	
Input Voltage	V _{IN}			1.62		3.60	V	
Input Undervoltage Lockout	V _{UVLO}	V _{IN} rising or falling (180mV typical hysteresis)		1.30		1.60	V	
Output Voltage Accuracy		I _{OUT} = 1mA to 300mA, V _{IN} = (V _{OUT} + 0.5V) to +3.6V	,		±0.5	+2.5	%	
Maximum Output Current	lout	Continuous		300			mA _{RMS}	
Current Limit	I _{LIM}	Vout = 96% of nominal value		450	550	650	mA	
		No load			70	140		
Ground Current	IQ	I _{OUT} = 300mA		90		μΑ		
		Dropout (Note 2)			70		1	
Dropout Voltage	V _{IN} - V _{OUT}	I _{OUT} = 300mA, V _{OUT} ≥ 1.8V (Note 2)			100	200	mV	
Load Regulation	ΔV_{LDR}	I _{OUT} = 1mA to 300mA			0.02	0.3	%	
Line Regulation	ΔV_{LNR}	$V_{IN} = (V_{OUT} + 0.5V)$ to +3.6V, $I_{OUT} = 1$ mA		-0.15	+0.01	+0.15	%/V	
Output Noise		10Hz to 100kHz, I _{OUT} = 10mA, V _{OUT} = 1.5V			86		μV _{RMS}	
PSRR		$f < 1kHz, I_{OUT} = 10mA$			70		dB	
SHUTDOWN								
Shutdown Supply Current	loff	SHDN = GND	$T_A = +25^{\circ}C$		0.001	1	μΑ	
Shataowii Supply Current	IOFF	SHIDIN = CIND	$T_A = +85^{\circ}C$		0.01		μΑ	
SHDN Input Logic Levels	VIH	$V_{IN} = 1.62V \text{ to } 3.6V$ $V_{IN} = 1.62V \text{ to } 3.6V$		1.4			V	
31 IDIN ITIPUT LOGIC Levels	VIL					0.6	V	
SHDN Input Bias Current	ISHDN	V _{SHDN} = 0V or 3.6V	$T_A = +25^{\circ}C$		1	100	nA	
or ibit input bias current	12HDIN	12HDIN - 01 01 0.01	$T_A = +85^{\circ}C$		5		II/A	
Turn-On Delay		From SHDN high to OUT high		90		μs		

2 ______M/XI/M

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = (V_{OUT} + 0.5V) \text{ or } 1.8V, \text{ whichever is greater}; \overline{SHDN} = IN, C_{IN} = 1\mu\text{F}, C_{OUT} = 4.7\mu\text{F}, T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at $T_{A} = +25^{\circ}\text{C}$.) (Note 1)

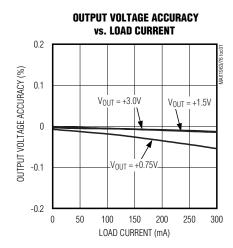
PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS	
RESET OUTPUT								
Reset Threshold Accuracy		Vout falling (1.7% typical hy	steresis)	80	82.5	85	%Vout	
RESET Output Low Voltage	IRESET = 100µA			1	100	\/		
RESET Output Low Voltage	V _{OL}	$V_{IN} = +1.0V$, $I_{\overline{RESET}} = 100\mu A$			30	400	mV	
RESET Output High Leakage	ГОН	V _{RESET} = 3.6V, RESET not asserted	$T_A = +25^{\circ}C$		0.001	1		
NESET Output High Leakage			$T_A = +85^{\circ}C$		0.01		μA	
Poset Dolov	+	From VouT high to RESET	MAX1963A	2.2	3.2	5.5		
Reset Delay	t _{RP}	rising	MAX1976A	70	100	160	ms	
THERMAL PROTECTION	THERMAL PROTECTION							
Thermal-Shutdown Temperature	TSHDN			+165	•	°C		
Thermal-Shutdown Hysteresis	ΔTSHDN				15	•	°C	

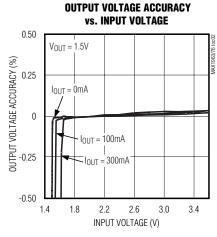
Note 1: Limits are 100% production tested at $T_A = +25$ °C. Limits over the operating temperature range are guaranteed by design.

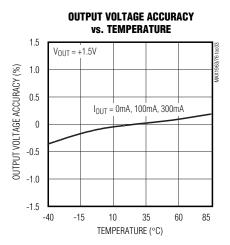
Note 2: The dropout voltage is defined as V_{IN} - V_{OUT}, when V_{OUT} is 4% lower than the value of V_{OUT} when V_{IN} = V_{OUT} + 0.5V.

_Typical Operating Characteristics

(V_{IN} = (V_{OUT} + 0.5V) or 1.8V, whichever is greater; SHDN = IN, C_{IN} = 1μF, C_{OUT} = 4.7μF, T_A = +25°C, unless otherwise noted.)

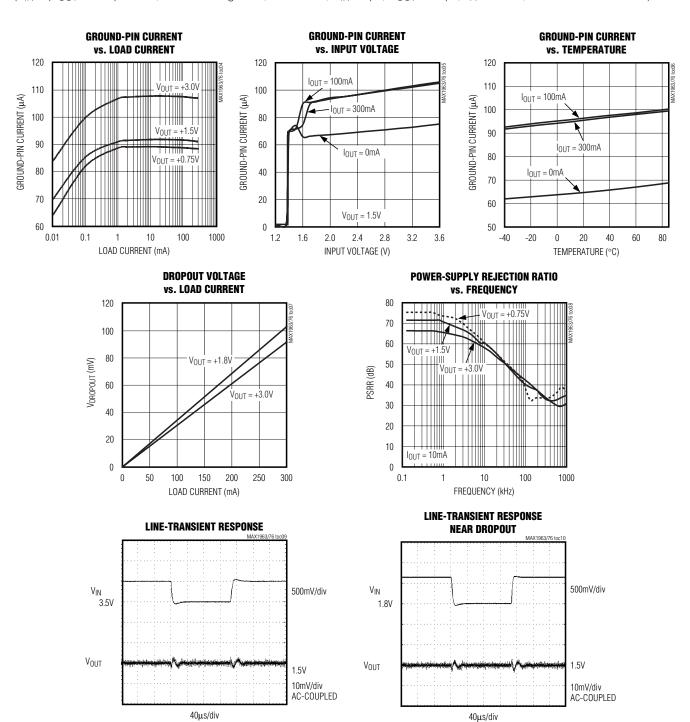






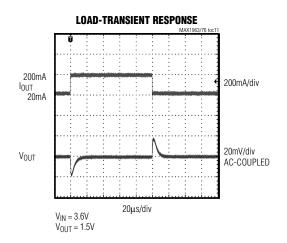
Typical Operating Characteristics (continued)

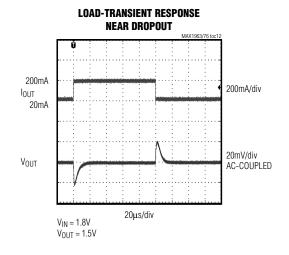
 $(V_{IN} = (V_{OUT} + 0.5V))$ or 1.8V, whichever is greater; $\overline{SHDN} = IN$, $C_{IN} = 1\mu F$, $C_{OUT} = 4.7\mu F$, $T_A = +25$ °C, unless otherwise noted.)

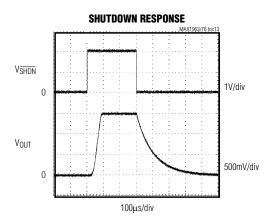


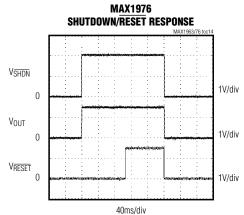
Typical Operating Characteristics (continued)

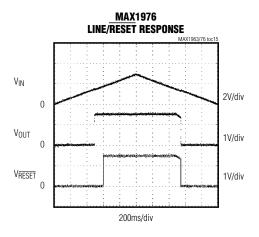
 $(V_{IN} = (V_{OUT} + 0.5V))$ or 1.8V, whichever is greater; $\overline{SHDN} = IN$, $C_{IN} = 1\mu F$, $C_{OUT} = 4.7\mu F$, $T_A = +25$ °C, unless otherwise noted.)











Pin Description

	PIN			FUNCTION	
THIN SOT23	6-PIN TDFN (3mm x 3mm)	8-PIN TDFN (2mm x 2mm)	NAME		
1	6	8	IN	Regulator Input. Supply voltage can range from +1.62V to +3.6V. Bypass IN with at least a 1µF ceramic capacitor to GND (see the <i>Capacitor Selection and Regulator Stability</i> section).	
2	_	_	GND	Ground. GND also functions as a heatsink. Solder to a large pad or circuit-board ground plane to maximize SOT23 power dissipation.	
_	4	5	GND	Ground	
3	5	6	SHDN	Active-Low Shutdown Input. A logic-low reduces supply current to below 1μA. Connect to IN or logic-high for normal operation.	
4	3	4	RESET	Open-Drain, Active-Low Reset Output. RESET rises 3.2ms (MAX1963A) or 100ms (MAX1976A) after the output has achieved regulation. RESET falls immediately if V _{OUT} drops below 82.5% of its nominal voltage, or if the MAX1963A/MAX1976A are shut down.	
5	2	3	I.C.	Internally Connected. Leave unconnected or connect to GND.	
6	1	1	OUT	Regulator Output. Sources up to 300mA. Bypass with a 4.7µF low-ESR ceramic capacitor to GND.	
_	_	2, 7	N.C.	No Connection. Not internally connected.	
_	_	_	EP	Ground (TDFNs only). EP also functions as a heatsink. Solder EP to a large pad or circuit-board ground plane to maximize TDFN power dissipation.	

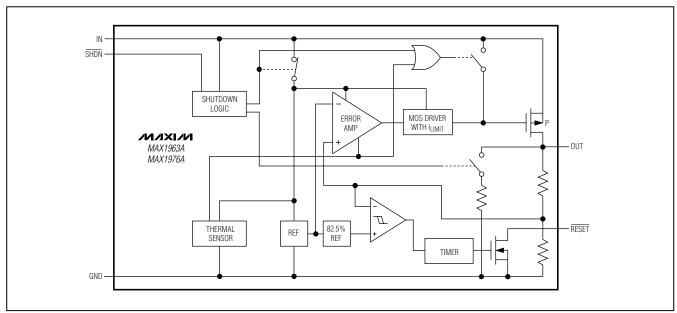


Figure 1. Functional Diagram

Detailed Description

The MAX1963A/MAX1976A are low-dropout, high-accuracy, low-quiescent-current linear regulators designed primarily for battery-powered applications. These devices supply loads up to 300mA and are available with preset output voltages from +0.75V to +3.0V. As illustrated in Figure 1, the MAX1963A/MAX1976A consist of a reference, an error amplifier, a p-channel pass transistor, an internal feedback voltage-divider, and a power-good comparator.

The reference is connected to the error amplifier, which compares this reference with the feedback voltage and amplifies the difference. If the feedback voltage is lower than the reference voltage, the pass-transistor gate is pulled lower, which allows more current to pass to the output and increases the output voltage. If the feedback voltage is too high, the pass-transistor gate is pulled up, allowing less current to pass to the output.

Internal p-Channel Pass Transistor

The MAX1963A/MAX1976A feature a 0.33Ω (RDS(ON)) p-channel MOSFET pass transistor. Unlike similar designs using pnp pass transistors, p-channel MOSFETs require no base drive, which reduces quiescent current. The pnp-based regulators also waste considerable current in dropout when the pass transistor saturates and use high base-drive currents under large loads. The MAX1963A/MAX1976A do not suffer from these problems and consume only 90μ A (typ) of quiescent current under heavy loads, as well as in dropout.

Shutdown

Pull \overline{SHDN} low to enter shutdown. During shutdown, the output is disconnected from the input, an internal 1.5k Ω resistor pulls OUT to GND, \overline{RESET} is actively pulled low, and the supply current drops below 1 μ A.

RESET Output

The MAX1963A/MAX1976A microprocessor (μ P) supervisory circuitry asserts a guaranteed logic-low reset during power-up, power-down, and brownout conditions down to +1V. RESET asserts when V_{OUT} is below the reset threshold and remains asserted for at least t_{RP} after V_{OUT} rises above the reset threshold of regulation.

Current Limit

The MAX1963A/MAX1976A monitor and control the pass transistor's gate voltage, limiting the output current to 450mA (min). If the output exceeds I_{LIM}, the MAX1963A/MAX1976A output voltage drops.

Thermal-Overload Protection

Thermal-overload protection limits total power dissipation in the MAX1963A/MAX1976A. When the junction

temperature exceeds $T_J = +165^{\circ}\text{C}$, a thermal sensor turns off the pass transistor, allowing the IC to cool. The thermal sensor turns the pass transistor on again after the junction temperature cools by 15°C, resulting in a pulsed output during continuous thermal-overload conditions. Thermal-overload protection safeguards the MAX1963A/MAX1976A in the event of fault conditions. For continuous operation, do not exceed the absolute maximum junction-temperature rating of $T_{JJ} = +150^{\circ}\text{C}$.

Operating Region and Power Dissipation

The MAX1963A/MAX1976A maximum power dissipation depends on the thermal resistance of the IC package and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The power dissipated in the device is $P = I_{OUT} \times (V_{IN} - V_{OUT})$. The maximum allowed power dissipation is:

$$P_{MAX} = (T_{J(MAX)} - T_{A}) / (\theta_{JC} + \theta_{CA})$$

where $(T_{J(MAX)} - T_A)$ is the temperature difference between the MAX1963A/MAX1976A die junction and the surrounding air, θ_{JC} is the thermal resistance of the junction to the case, and θ_{CA} is the thermal resistance from the case through the PC board, copper traces, and other materials to the surrounding air. For best heatsinking, expand the copper connected to the exposed paddle or GND.

The MAX1963A/MAX1976A deliver up to 300mA and operate with an input voltage up to +3.6V. However, when using the 6-pin SOT23 version, high output currents can only be sustained when the input-output differential voltage is less than 2V, as shown in Figure 2.

The maximum allowed power dissipation for the 6-pin TDFN is 1.951W at $T_A = +70^{\circ}C$. Figure 3 shows that the maximum input-output differential voltage is not limited by the TDFN package power rating.

Applications Information

Capacitor Selection and Regulator Stability

Capacitors are required at the MAX1963A/MAX1976A input and output for stable operation over the full temperature range and with load currents up to 300mA. Connect a 1µF ceramic capacitor between IN and GND and a 4.7µF low-ESR ceramic capacitor between OUT and GND. The input capacitor (C_{IN}) lowers the source impedance of the input supply. Use larger output capacitors to reduce noise and improve load-transient response, stability, and power-supply rejection.

The output capacitor's equivalent series resistance (ESR) affects stability and output noise. Use output

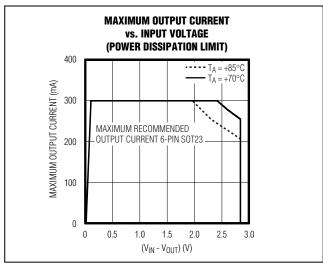


Figure 2. Power Operating Regions for the 6-Pin SOT23: Maximum Output Current vs. Input Voltage

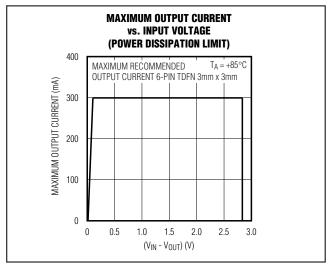


Figure 3. Power Operating Regions for the 6-Pin TDFN: Maximum Output Current vs. Input Voltage

capacitors with an ESR of $30m\Omega$ or less to ensure stability and optimize transient response. Surface-mount ceramic capacitors have very low ESR and are commonly available in values up to $10\mu F$. Connect C_{IN} and C_{OUT} as close to the MAX1963A/MAX1976A as possible to minimize the impact of PC board trace inductance.

Noise, PSRR, and Transient Response

The MAX1963A/MAX1976A are designed to operate with low dropout voltages and low quiescent currents in battery-powered systems while still maintaining good noise, transient response, and AC rejection. See the *Typical Operating Characteristics* for a plot of Power-Supply Rejection Ratio (PSRR) versus Frequency. When operating from noisy sources, improved supplynoise rejection and transient response can be achieved by increasing the values of the input and output bypass capacitors and through passive filtering techniques.

The MAX1963A/MAX1976A load-transient response (see the *Typical Operating Characteristics*) shows two components of the output response: a near-zero DC shift from the output impedance due to the load-current change, and the transient response. A typical transient response for a step change in the load current from 20mA to 200mA is 20mV. Increasing the output capacitor's value and decreasing the ESR attenuates the overshoot.

Input-Output (Dropout) Voltage

A regulator's minimum input-output voltage difference (dropout voltage) determines the lowest usable supply voltage. In battery-powered systems, this determines the useful end-of-life battery voltage. Because the MAX1963A/MAX1976A use a p-channel MOSFET pass transistor, the dropout voltage is a function of drain-to-source on-resistance (RDS(ON) = 0.33Ω) multiplied by the load current (see the *Typical Operating Characteristics*).

 $V_{DROPOUT} = V_{IN} - V_{OUT} = 0.33\Omega \times I_{OUT}$ e MAX1963A/MAX1976A ground current reduce

The MAX1963A/MAX1976A ground current reduces to 70µA in dropout.

8 ______ **/\!X\/**

Selector Guide

VOUT	SUFFIX	MAX1963A TOP MARK			MAX1976A TOP MARK			
(V)	SUFFIX	SOT	TDFN (3mm x 3mm)	TDFN (2mm x 2mm)	SOT	TDFN (3mm x 3mm)	TDFN (2mm x 2mm)	
0.75	075	AACJ	ALM	_	AACU	ALX	_	
0.85	085	_	_	_	AACV	ALY	_	
0.90	090	AACK	ALN	_	AACW	ALZ	_	
1.00	100	AACL	ALO	_	AACX	AMA	_	
1.10	110	AACM	ALP	_	AACY	AMB	_	
1.20	120	AACN	ALQ	_	AACZ	AMC	_	
1.30	130	AACO	ALR	_	AADA	AMD	AAD	
1.50	150	AACP	ALS	_	AADB	AME	AAE	
1.60	160	_	_	_	AADC	AMF	_	
1.80	180	AACQ	ALT	_	AADD	AMG	_	
1.85	185	AACR	ALU	_	AADE	AMH	_	
2.50	250	AACS	ALV	_	AADF	AMI	_	
2.85	285	_	_	_	AADG	AMJ	_	
3.00	300	AACT	ALW		AADH	AMK	_	
1.20	120/V	_	_	_	_	AUO	_	
1.50	150/V	_	_	_	_	AVI	_	
1.80	180/V		_	_	_	AUP	_	

Note: Standard voltage options, shown in **bold**, are available. Contact the factory for other output voltages between 1.5V and 4.5V. Minimum order quantity is 15,000 units.

Chip Information

Package Information

For the latest package outline information and land patterns (footprints), go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
6 TDFN-EP	T633+2	<u>21-0137</u>	<u>90-0058</u>
6 SOT-23	Z6+1	<u>21-0114</u>	90-0242
8 TDFN-EP	T822+1	<u>21-0168</u>	90-0064

PROCESS: BiCMOS

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	5/05	Initial release	_
1	5/12	Added lead-free packaging information to the data sheet, updated <i>Selector Guide</i> and <i>Pin Description</i>	1, 6, 9

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Maxim Integrated:

<u>MAX1976AETA120+T</u> <u>MAX1976AETT100+T</u> <u>MAX1963AEZT120+T</u> <u>MAX1976AEZT120+T</u> <u>MAX1976AEZT160+T</u> <u>MAX1963AEZT075+T</u> <u>MAX1963AEZT100+T</u> <u>MAX1976AETT120+T</u> <u>MAX1976AETT180+T</u> <u>MAX1976AEZT100+T</u> <u>MAX1976AEZT250+T</u> <u>MAX1976AETT150+T</u>